



The XM520, a general purpose chip mounter with the best-in-class productivity and quality enhancements, also has flexible applicability to product types and allows a wide range of line combinations and options. Its Innovative functions maximize user convenience to enable rapid job change.



Model Name			XM520
Alignment			Fly Camera, Stage Camera
The Number of Spindles			2 Gantry x 10 Spindle
Placement Speed			100,000 CPH (Optimum)
Placement Accuracy	Chip		±22 μm @ Cpk ≥ 1.0
	IC		±25 μm @ Cpk ≥ 1.0
Component Range			0201 ~ 🗆 55 mm, L150 mm Connector , H15 mm
PCB Size (mm)	Min.		L50 x W40
	Max.	Single Mode	L625 x W460 ~L1,200 x W590**
		Dual Mode	L625 x W250 ~L1,200 x W315**
PCB Thickness (mm)			0.3 ~ 4.2
Feeder Capacity (8 mm standard)			120 ea / 112 ea (Docking Cart)
External Dimension (Standard)			L1,430 x D1,900 x H1,994

* The specifications may vary depending on the application of options (Please contact our sales person for more details)

** L1,200mm option is a specialized specification and is discussed with the sales representative



Best speed in 10 Spindle solution Max. 100,000 CPH

Its best-in-class speed and applicability to wide head pitch (15mm) and height (H10mm (Fly), 15mm (Stage)) extends the range of components that can be simultaneously picked up, achieving high actual productivity for components from microchips to odd-shape components.



$\frac{\text{Best accuracy in class}}{\pm 22 \,\mu\text{m} @ \text{cpk} \ge 1.0}$

Achieves best-in-class placement accuracy and maintains high component placement quality by automating quality control of runtime calibration, nozzle maintenance units, etc.

Flexible Production

Wide Applicability to Components

Possible to place components from 0201 microchips up to \Box 55 mm and L150 mm components, with a height of up to 15 mm.



Various Line Combinations Owing to Flexible Applicability to PCBs

Applicable to PCBs of maximum $L1200 \times 590 \text{ mm}$, allowing optimal in-line combination to suit the user's production environment.



Two Work Zones Increase Actual Productivity

After placing components on the previous PCB (A), it is possible to place components on the next PCB (B) waiting at the nearby work zone, thus reducing the transfer time to increase productivity.

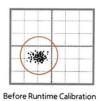


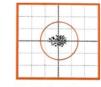


Convenient Operation

Maintains Placement Accuracy through Automatic Calibration during Production

Maintains placement accuracy continuously by performing major calibrations at the set time during production.





After Runtime Calibration

Automating Placement Point Teaching

By automating the inspection and modification of the placement points of standard chips, the time required for checking and fine adjustment of the placement coordinates during job change has been significantly reduced.



Zero Waste of Components during Initial (Sample) Production

Realizes zero waste of components that occurs during job change without dumping the component to which a recognition error occurred during sample production but by immediately editing component information and PCB coordinate and placing components.



Performs operation in the sample production mode without dumping components



Starts production after registering the component in the component library



The above items may differ depending on actual operating conditions. For the details related to options, please contact the person responsible for sales.

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